

MAXIMUM RATINGS

| Screen | Parameter | Symbol | Min | Max | Units | Test Conditions |
|--------|--|-----------|-----|------|-------|-----------------|
| BD | Collector-Emitter Voltage | V_{CES} | -- | 75 | V | -- |
| BD | Emitter-Base Voltage | V_{EBO} | -- | 2 | V | -- |
| BD | Storage Temperature Range | T_{STG} | -55 | +150 | °C | -- |
| BD | Operating Junction Temperature Range | T_J | -55 | +200 | °C | -- |
| Note | Screen 'BD' = parameter qualified By Design. | | | | | |

THERMAL CHARACTERISTICS

| Screen | Parameter | Symbol | Min | Max | Units | Test Conditions |
|--------|--|--------------|-----|-----|-------|---|
| BD | Thermal Resistance | $R_{TH(JC)}$ | TBD | | °C/W | $V_{CC}=50V$, Pulse format=TACAN, $T_F=25\pm 5^\circ C$, $P_{IN}=6W$, $N_C=55\%$ |
| Note | Screen 'BD' = parameter qualified By Design. | | | | | |

PROCESSING SPECIFICATIONS

| Screen | Parameter | Symbol | Min | Max | Units | Test Conditions |
|--------|--|--------|-----|-----|-------|---|
| 100% | DC Wafer Probe | -- | -- | -- | -- | Per Integra specification. |
| Q1 | Wafer DC and RF Qualification | -- | -- | -- | -- | Per Integra specification. |
| LM | Wire Bond Strength | -- | -- | -- | -- | Line monitor per Integra specification. |
| 100% | Pre-cap visual inspection | -- | -- | -- | -- | Per Integra specification |
| 100% | Gross leak test | -- | -- | -- | -- | MIL-STD-750D, Method 1071, Test Condition C |
| Note | Screen 'Q1' = parameter is qualified by assembly and test of 3 pieces minimum per wafer. | | | | | |
| Note | Screen 'LM' = parameter is qualified by assembly line monitor. | | | | | |

DC ELECTRICAL CHARACTERISTICS

| Screen | Parameter | Symbol | Min | Max | Units | Test Conditions |
|--------|---|------------|-----|-----|---------|--|
| 100% | Collector-Emitter Breakdown Voltage | BV_{CES} | 75 | -- | V | $I_C = 40mA$, $V_{BE} = 0V$, $T_F = 25\pm 5^\circ C$. |
| 100% | Zero Base Voltage Collector Leakage Current | I_{CES} | -- | 100 | μA | $V_{CE} = 50V$, $V_{BE} = 0V$, $T_F = 25\pm 5^\circ C$. |
| 100% | DC Current Gain | H_{FE} | 20 | 100 | -- | $V_{CE} = 5V$, $I_C = 500mA$, $T_F = 25\pm 5^\circ C$. |

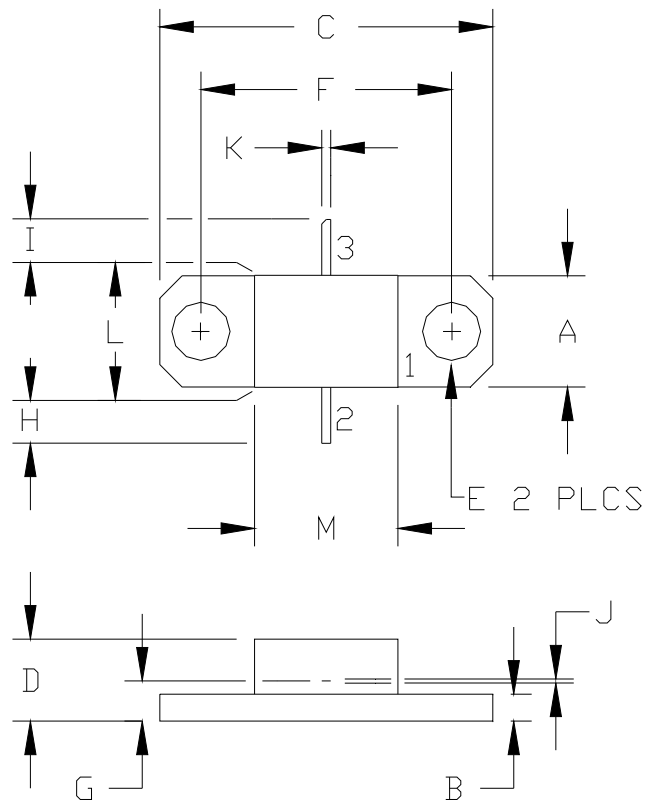
RF ELECTRICAL CHARACTERISTICS

| Screen | Parameter | Symbol | Min | Max | Units | Test Conditions |
|--------|--|---------------|-------|-------|-------|---|
| 100% | Input Return Loss | RL | -18 | -9 | dB | $V_{CC}=50V$, $P_{IN}=6W$, Pulse = Note 2, $T_F=25\pm5^\circ C$, $F=F1$. |
| BD | Maximum Overdrive | $P_{IN(MAX)}$ | -- | 8 | W | $V_{CC}=50V$, Pulse = Note 2, $T_F=25\pm5^\circ C$, $F=F1$. |
| 100% | Power Gain | G_P | 10.67 | 13.17 | dB | $V_{CC}=50V$, $P_{IN}=6W$, Pulse = Note 2, $T_F=25\pm5^\circ C$, $F=F1$ |
| 100% | Output Power | P_{out} | 70.0 | 124.0 | W | $V_{CC}=50V$, $P_{IN}=6W$, Pulse = Note 2, $T_F=25\pm5^\circ C$, $F=F1$ |
| 100% | Collector Efficiency ($P_o/I_c/V_{CC}$) | N_C | 50 | 80 | % | $V_{CC}=50V$, $P_{IN}=6W$, Pulse = Note 2, $T_F=25\pm5^\circ C$, $F=F1$. |
| 100% | Pulse Amplitude Droop | Droop | -0.5 | 0.5 | dB | $V_{CC}=50V$, $P_{IN}=6W$, Pulse = Note 2, $T_F=25\pm5^\circ C$, $F=F1$. |
| 100% | Gain Flatness | dG | 0 | 1.5 | dB | Delta between highest gain and lowest gain from 960-1215MHz |
| 100% | Stability into 1.5:1 VSWR | VSWR-S | -- | -- | -- | $V_{CC}=50V$, $P_{IN}=6W$, Pulse = Note 2, $T_F=25\pm5^\circ C$, $F=F1$. Rotate 1.5:1 output VSWR through 360° Phase. No oscillatory or pulse break-up characteristics allowed on detected output pulse. |
| 100% | Load Mismatch Tolerance | VSWR-LMT | 3:1 | -- | -- | $V_{CC}=50V$, $P_{IN}=6W$, Pulse = Note 2, $T_F=25\pm5^\circ C$, $F=F1$. Rotate 3:1 output VSWR through 360° Phase. Survival. |
| Note 1 | F1 = 960/1090/1215 MHz. | | | | | |
| Note 2 | Pulse width = TACAN (10us, 10%) | | | | | |
| Note 3 | T_F = Device flange temperature. | | | | | |
| Note 4 | Screen 'BD' = parameter qualified By Design. | | | | | |

RF TEST FIXTURE IMPEDANCE CHARACTERISTICS

| Frequency (MHz) | Z_{IF} (Ω) | Z_{OF} (Ω) |
|----------------------|-----------------------|-----------------------|
| 960 | 3.77 -j4.20 | 12.03 -j1.42 |
| 1090 | 4.00 -j2.70 | 10.60 +j1.04 |
| 1215 | 4.87 -j1.49 | 10.41 +j3.77 |
| Impedance Definition | | |

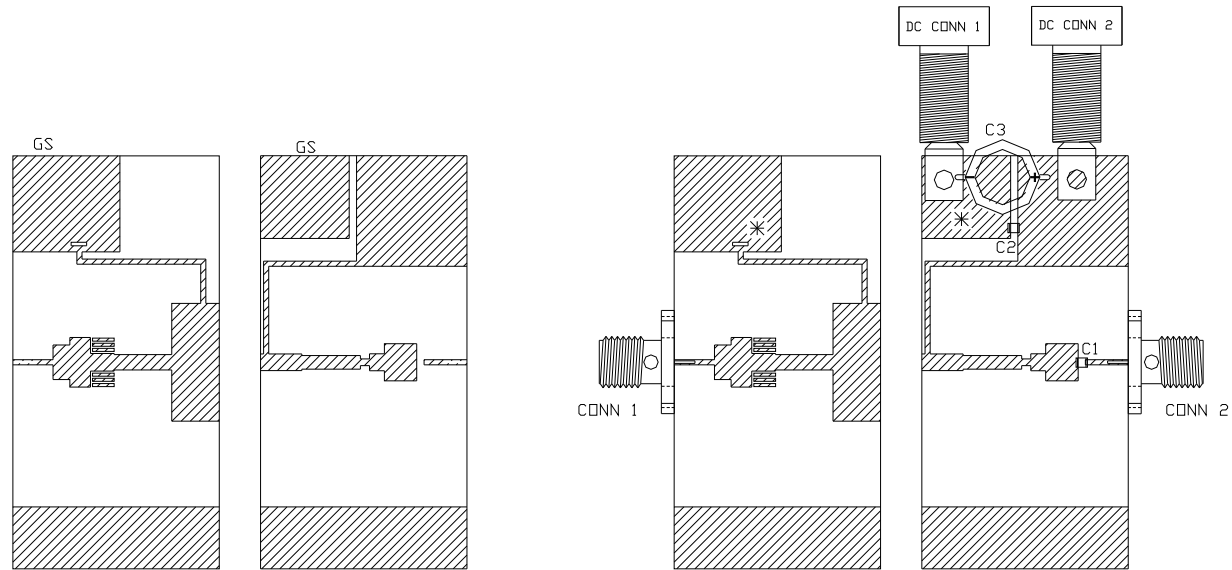
PACKAGE DIMENSIONAL OUTLINE DRAWING



| DIM | INCHES | | MILLIMETERS | |
|-----|--------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.243 | 0.253 | 6.17 | 6.43 |
| B | 0.055 | 0.065 | 1.40 | 1.65 |
| C | 0.739 | 0.749 | 18.77 | 19.02 |
| D | 0.178 | 0.188 | 4.52 | 4.78 |
| E | 0.125 | 0.135 | 3.18 | 3.43 |
| F | 0.555 | 0.565 | 14.10 | 14.35 |
| G | 0.082 | 0.092 | 2.08 | 2.34 |
| H | 0.040 | 0.200 | 1.02 | 5.08 |
| I | 0.040 | 0.200 | 1.02 | 5.08 |
| J | 0.004 | 0.006 | 0.10 | 0.15 |
| K | 0.055 | 0.065 | 1.40 | 1.65 |
| L | 0.245 | 0.255 | 6.22 | 6.48 |
| M | 0.315 | 0.325 | 8.00 | 8.26 |

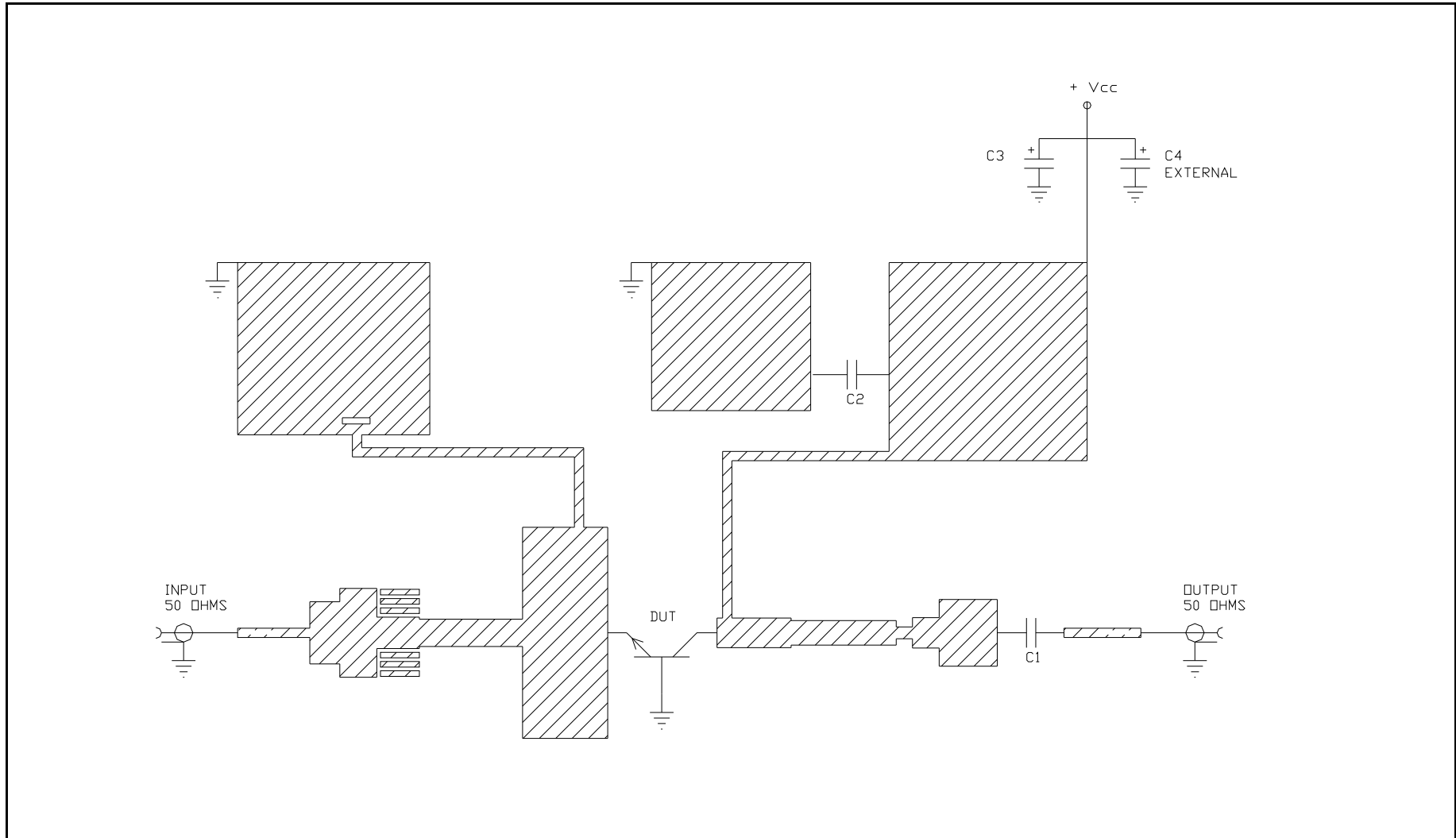
| PIN SCHEDULE | |
|--------------|-----------|
| 1 | BASE |
| 2 | EMITTER |
| 3 | COLLECTOR |

RF TEST FIXTURE ASSEMBLY AND PART LIST



| COMPONENT | DESCRIPTION |
|---------------------------|--|
| DUT | TRANSISTOR #IB0912M70, MOUNT HARD TO THE RIGHT |
| PC BOARD | ROGERS #R03010 .025" 1oz Cu |
| C1, C2 | CHIP CAPACITOR ATC100A-100 pF |
| C3 | ELECTROLYTIC CAPACITOR 68uF / 63V |
| C4 (NOT SHOWN) | ELECTROLYTIC CAPACITOR 4700uF/50V |
| GS (2 PLACES) | GROUND SHIM, COPPER, TH=0.001" |
| CONN 1, CONN 2 (2 PLACES) | SMA CONNECTOR, DS #2052-5636-02 |
| INPUT PC BOARD CARRIER | 2 INCH BRASS-03 (1.0") |
| OUTPUT PC BOARD CARRIER | 2 INCH BRASS-03 (1.0") |
| TRANSISTOR CARRIER | 2 INCH COPPER-01 (P32) |
| TRANSISTOR CLAMP | NORYL CLAMP-01 (P32) |
| ALUMINUM HEATSINK | 2 INCH HEATSINK-09 |
| DC CONN1 | BANANA JACK, BLACK |
| DC CONN 2 | BANANA JACK, RED |
| NOTE | FIXTURE HARDWARE DRAWINGS AVAILABLE ON REQUEST |

RF TEST FIXTURE ELECTRICAL SCHEMATIC



DEFINITIONS

| Data Sheet Status | |
|--|---|
| Proposed Specification | This data sheet contains proposed specifications. |
| Preliminary Specification | This data sheet contains specifications based on preliminary measurements and data. |
| Product Specification | This data sheet contains final product specifications. |
| Maximum Ratings | |
| Stress above one or more of the maximum ratings may cause permanent damage to the device. These are maximum ratings only and operation of the device at these or at any other conditions above those given in the characteristics sections of the specification is not implied. Exposure to maximum values for extended periods of time may affect device reliability. | |

WARNING

| Product and environmental safety - toxic materials |
|--|
| This product contains beryllium oxide. The product is entirely safe provided that the BeO base is not damaged. All persons who handle, use or dispose of this product should be aware of its nature and of the necessary safety precautions. After use, dispose of as chemical or special waste according to the regulations applying at the location of the user. It must never be thrown out with general or domestic waste. |

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